



## Material Content Data Sheet



Sales Product Name	BTM7751G			Issued		29. August 2013		
MA#	MA000913874							
Package	PG-DSO-28-22			Weight*		810.55 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.033	1.36	1.36	13612	13612
leadframe	inorganic material	phosphorus	7723-14-0	0.072	0.01		89	
	non noble metal	zinc	7440-66-6	0.288	0.04		355	
	non noble metal	iron	7439-89-6	5.754	0.71		7099	
	non noble metal	copper	7440-50-8	233.637	28.82	29.58	288247	295790
wire	non noble metal	aluminium	7429-90-5	1.728	0.21	0.21	2132	2132
encapsulation	organic material	carbon black	1333-86-4	1.098	0.14		1355	
	plastics	epoxy resin	-	78.525	9.69		96879	
	inorganic material	silicondioxide	60676-86-0	469.504	57.92	67.75	579244	677478
leadfinish	non noble metal	tin	7440-31-5	4.913	0.61	0.61	6062	6062
plating	non noble metal	nickel	7440-02-0	0.196	0.02		242	
	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	noble metal	silver	7440-22-4	0.678	0.08	0.10	836	1079
glue	plastics	epoxy resin	-	0.546	0.07		673	
	noble metal	silver	7440-22-4	2.573	0.32	0.39	3174	3847
*deviation	< 10%	Sum in total:				100,00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com